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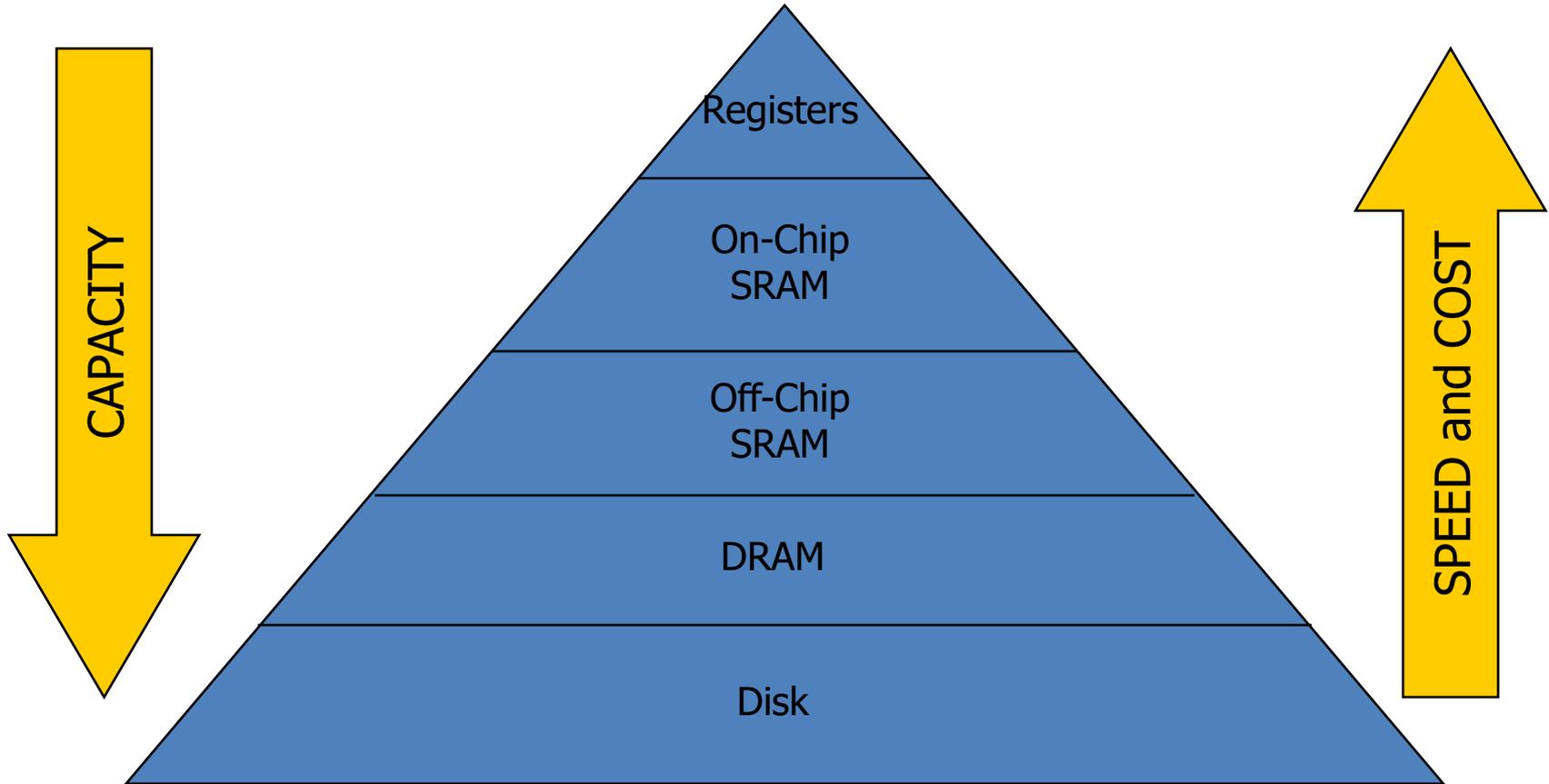
ECE/CS 552:

Main Memory and ECC

© Prof. Mikko Lipasti

Lecture notes based in part on slides created by Mark Hill, David Wood, Guri Sohi, John Shen and Jim Smith

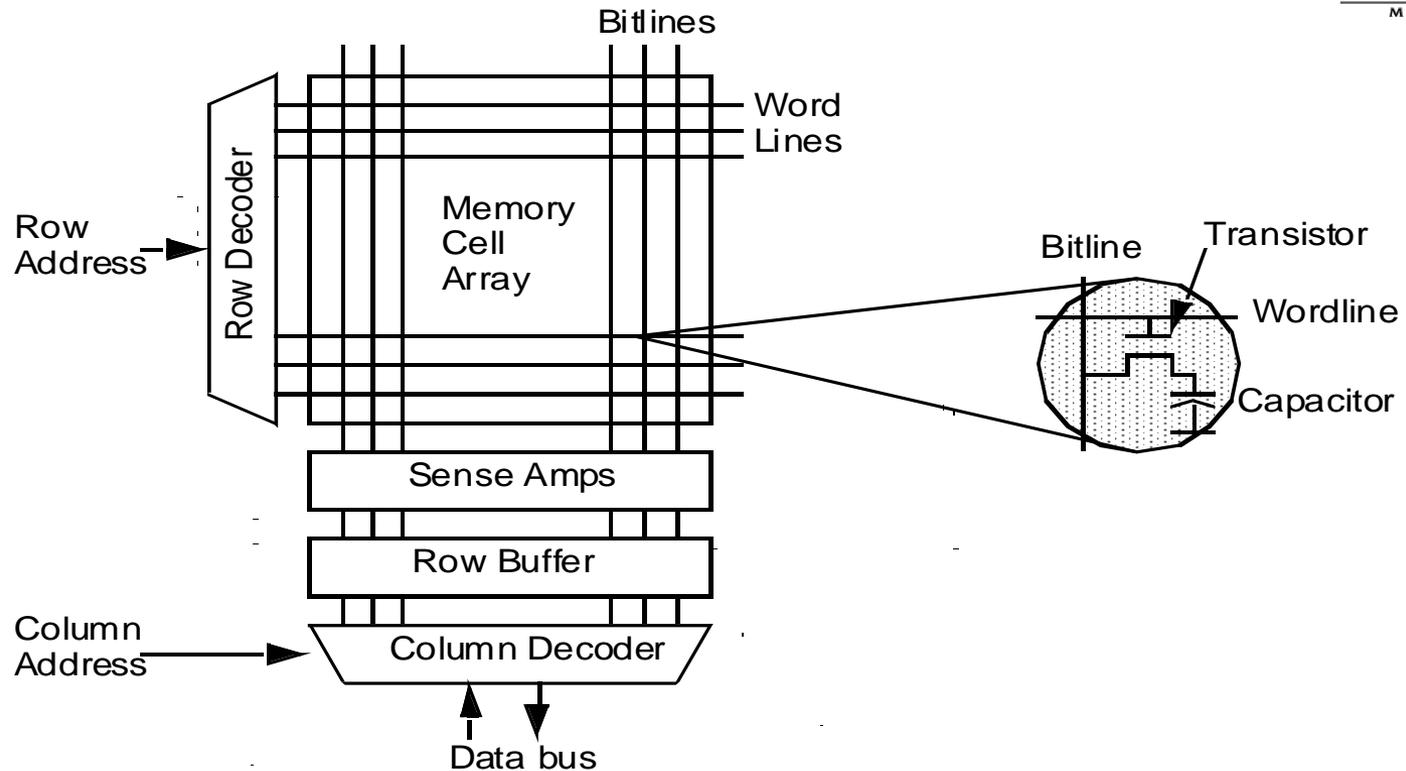
Memory Hierarchy



Main Memory Design

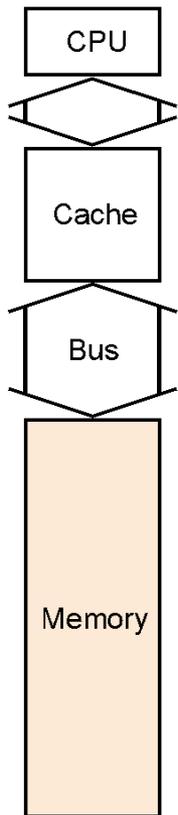
- Commodity DRAM chips
- Wide design space for
 - Minimizing cost, latency
 - Maximizing bandwidth, storage
- Susceptible to soft errors
 - Protect with ECC (SECCDED)
 - ECC also widely used in on-chip memories, busses

DRAM Chip Organization

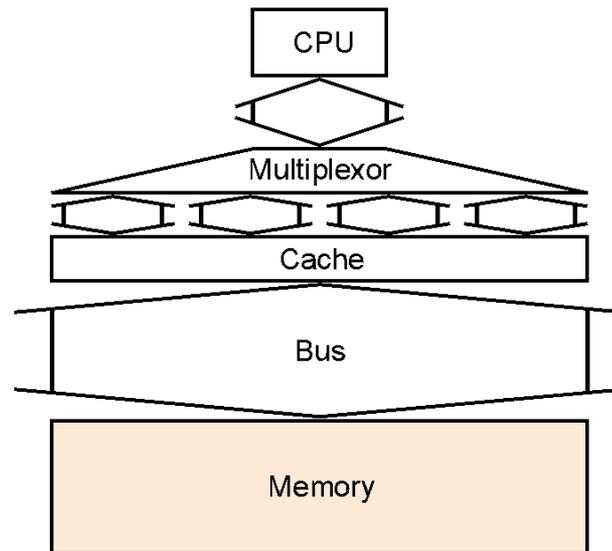


- Optimized for density, not speed
- Data stored as charge in capacitor
- Discharge on reads => destructive reads
- Charge leaks over time
 - refresh every 64ms
- Read entire row at once (RAS, page open)
- Read word from row (CAS)
- Burst mode (sequential words)
- Write row back (precharge, page close)

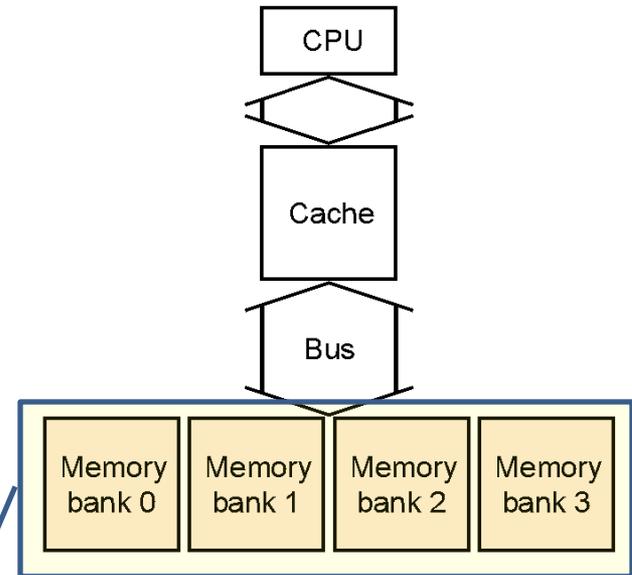
Main Memory Design



a. One-word-wide
memory organization



b. Wide memory organization



c. Interleaved memory organization

Single DRAM chip
has multiple
internal banks

Main Memory Access

- Each memory access (DRAM bus clocks, 10x CPU cycle time)
 - 5 cycles to send row address (page open or RAS)
 - 1 cycle to send column address
 - 3 cycle DRAM access latency
 - 1 cycle to send data (CAS latency = 1+3+1 = 5)
 - 5 cycles to send precharge (page close)
 - 4 word cache block
- One word wide: (r=row addr, c= col addr, d=delay, b=bus, p=precharge)

rrrrrcdddbcdddbcdddbcdddbppppp

- $5 + 4 * (1 + 3 + 1) = 25$ cycles delay
- 5 more busy cycles (precharge) till next command

Main Memory Access

- One word wide, burst mode (pipelined)

rrrrrcdddb

b

b

bppppp

- $5 + 1 + 3 + 4 = 13$ cycles
- Interleaving is similar, but words can be from different rows, each open in a different bank
- Four word wide memory:

rrrrrcdd**b**ppppp

- $5 + 1 + 3 + 1 = 9$ cycles

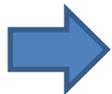
Error Detection and Correction

- Main memory stores a huge number of bits
 - Probability of bit flip becomes nontrivial
 - Bit flips (called soft errors) caused by
 - Slight manufacturing defects
 - Gamma rays and alpha particles
 - Electrical interference
 - Etc.
 - Getting worse with smaller feature sizes
- Reliable systems must be protected from soft errors via ECC (error correction codes)
 - Even PCs support ECC these days

Error Correcting Codes

- Probabilities:
 $P(1 \text{ word no errors}) > P(\text{single error}) > P(\text{two errors}) \gg P(>2 \text{ errors})$
- Detection - signal a problem
- Correction - restore data to correct value
- Most common
 - Parity - single error detection
 - SECDED - single error correction; double error detection
- Supplemental reading on course web page!

ECC Codes for One Bit



Power	Correct	#bits	Comments
Nothing	0,1	1	
SED	00,11	2	01,10 detect errors
SEC	000,111	3	001,010,100 => 0 110,101,011 => 1
SECDDED	0000,1111	4	One 1 => 0 Two 1's => error Three 1's => 1

ECC

# 1's	0	1	2	3	4
Result	0	0	Err	1	1

- Hamming distance
 - No. of bit flips to convert one valid code to another
 - All legal SECDED codes are at Hamming distance of 4
 - I.e. in single-bit SECDED, all 4 bits flip to go from representation for '0' (0000) to representation for '1' (1111)

ECC

- Reduce overhead by applying codes to a word, not a bit
 - Larger word means higher $p(\geq 2 \text{ errors})$

# bits	SED overhead	SECDED overhead
1	1 (100%)	3 (300%)
32	1 (3%)	7 (22%)
64	1 (1.6%)	8 (13%)
n	1 (1/n)	$1 + \log_2 n + \text{a little}$

64-bit ECC

- 64 bits data with 8 check bits
 dddd.....dccccccccc
- DIMM with 9x8-bit-wide DRAM chips = 72 bits
- Intuition
 - One check bit is parity
 - Other check bits point to
 - Error in data, or
 - Error in all check bits, or
 - No error

ECC

- To store (write)
 - Use data_0 to compute check_0
 - Store data_0 and check_0
- To load
 - Read data_1 and check_1
 - Use data_1 to compute check_2
 - Syndrome = $\text{check}_1 \text{ xor } \text{check}_2$
 - I.e. make sure check bits are equal

ECC Syndrome

Syndrome	Parity	Implications
0	OK	$\text{data}_1 == \text{data}_0$
$n \neq 0$	Not OK	Flip bit n of data_1 to get data_0
$n \neq 0$	OK	Signals uncorrectable error

4-bit SECDED Code

Bit Position	001	010	011	100	101	110	111	
Codeword	C_1	C_2	b_1	C_3	b_2	b_3	b_4	P
C_1	X		X		X		X	
C_2		X	X			X	X	
C_3				X	X	X	X	
P	X	X	X	X	X	X	X	X

$$C_1 = b_1 \oplus b_2 \oplus b_4$$

$$C_2 = b_1 \oplus b_3 \oplus b_4$$

$$C_3 = b_2 \oplus b_3 \oplus b_4$$

$$P = \text{even_parity}$$

- C_n parity bits chosen specifically to:
 - Identify errors in bits where bit n of the index is 1
 - C_1 checks all odd bit positions (where LSB=1)
 - C_2 checks all positions where middle bit=1
 - C_3 checks all positions where MSB=1
- Hence, nonzero syndrome points to faulty bit

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